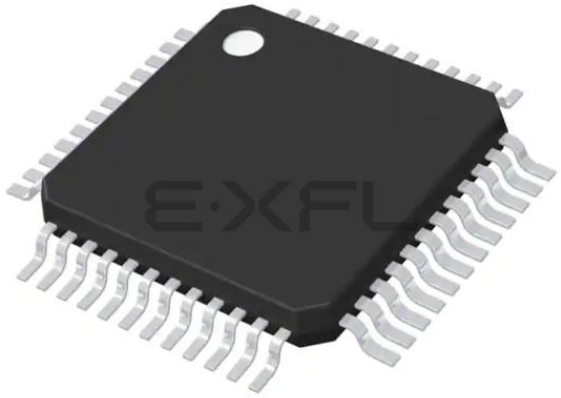
Infineon Technologies - SAK-XC886LM-8FFI 5V AC Datasheet



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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	XC800
Core Size	8-Bit
Speed	24MHz
Connectivity	LINbus, SSI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	34
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	1.75K x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 5.5V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	48-LQFP
Supplier Device Package	PG-TQFP-48
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/sak-xc886lm-8ffi-5v-ac

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8-Bit

XC886/888CLM

8-Bit Single Chip Microcontroller

Data Sheet

V1.2 2009-07

Microcontrollers

2.3 Pin Configuration

The pin configuration of the XC886, which is based on the PG-TQFP-48 package, is shown in **Figure 4**, while that of the XC888, which is based on the PG-TQFP-64 package, is shown in **Figure 5**.

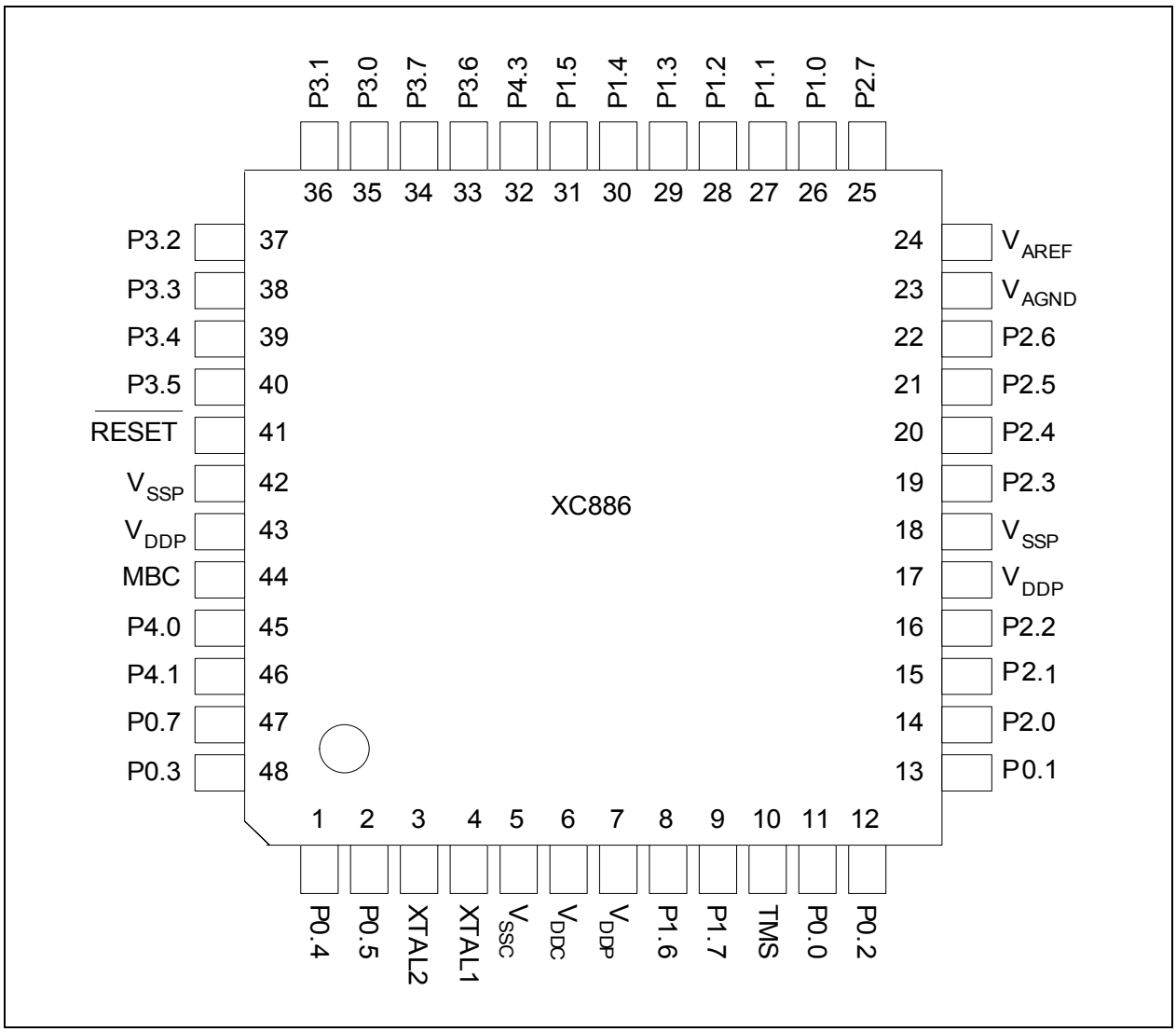


Figure 4 XC886 Pin Configuration, PG-TQFP-48 Package (top view)

code or data. Therefore, even though the ROM device contains either a 24-Kbyte or 32-Kbyte ROM, the maximum size of code that can be placed in the ROM is the given size less four bytes.

3.2.1 Memory Protection Strategy

The XC886/888 memory protection strategy includes:

- Read-out protection: The user is able to protect the contents in the Flash (for Flash devices) and ROM (for ROM devices) memory from being read
  - Flash protection is enabled by programming a valid password (8-bit non-zero value) via BSL mode 6.
  - ROM protection is fixed with the ROM mask and is always enabled.
- Flash program and erase protection: This feature is available only for Flash devices.

3.2.1.1 Flash Memory Protection

As long as a valid password is available, all external access to the device, including the Flash, will be blocked.

For additional security, the Flash hardware protection can be enabled to implement a second layer of read-out protection, as well as to enable program and erase protection.

Flash hardware protection is available only for Flash devices and comes in two modes:

- Mode 0: Only the P-Flash is protected; the D-Flash is unprotected
- Mode 1: Both the P-Flash and D-Flash are protected

The selection of each protection mode and the restrictions imposed are summarized in **Table 4**.

Table 4 Flash Protection Modes

Flash Protection	Without hardware protection	With hardware protection	
Hardware Protection Mode	-	0	1
Activation	Program a valid password via BSL mode 6		
Selection	Bit 4 of password = 0	Bit 4 of password = 1 MSB of password = 0	Bit 4 of password = 1 MSB of password = 1
P-Flash contents can be read by	Read instructions in any program memory	Read instructions in the P-Flash	Read instructions in the P-Flash or D-Flash
External access to P-Flash	Not possible	Not possible	Not possible

SYSCON0
System Control Register 0 **Reset Value: 04_H**

7	6	5	4	3	2	1	0
	0		**IMODE**	**0**	**1**	**0**	**RMAP**
	r		rw	r	r	r	rw

Field	Bits	Type	Description
RMAP	0	rw	**Interrupt Node XINTR0 Enable** 0 The access to the standard SFR area is enabled 1 The access to the mapped SFR area is enabled
1	2	r	**Reserved** Returns 1 if read; should be written with 1.
0	[7:5], 3,1	r	**Reserved** Returns 0 if read; should be written with 0.

Note: The RMAP bit should be cleared/set by ANL or ORL instructions.

3.2.2.2 Address Extension by Paging

Address extension is further performed at the module level by paging. With the address extension by mapping, the XC886/888 has a 256-SFR address range. However, this is still less than the total number of SFRs needed by the on-chip peripherals. To meet this requirement, some peripherals have a built-in local address extension mechanism for increasing the number of addressable SFRs. The extended address range is not directly controlled by the CPU instruction itself, but is derived from bit field PAGE in the module page register MOD_PAGE. Hence, the bit field PAGE must be programmed before accessing the SFR of the target module. Each module may contain a different number of pages and a different number of SFRs per page, depending on the specific requirement. Besides setting the correct RMAP bit value to select the SFR area, the user must also ensure that a valid PAGE is selected to target the desired SFR. A page inside the extended address range can be selected as shown in **Figure 9**.

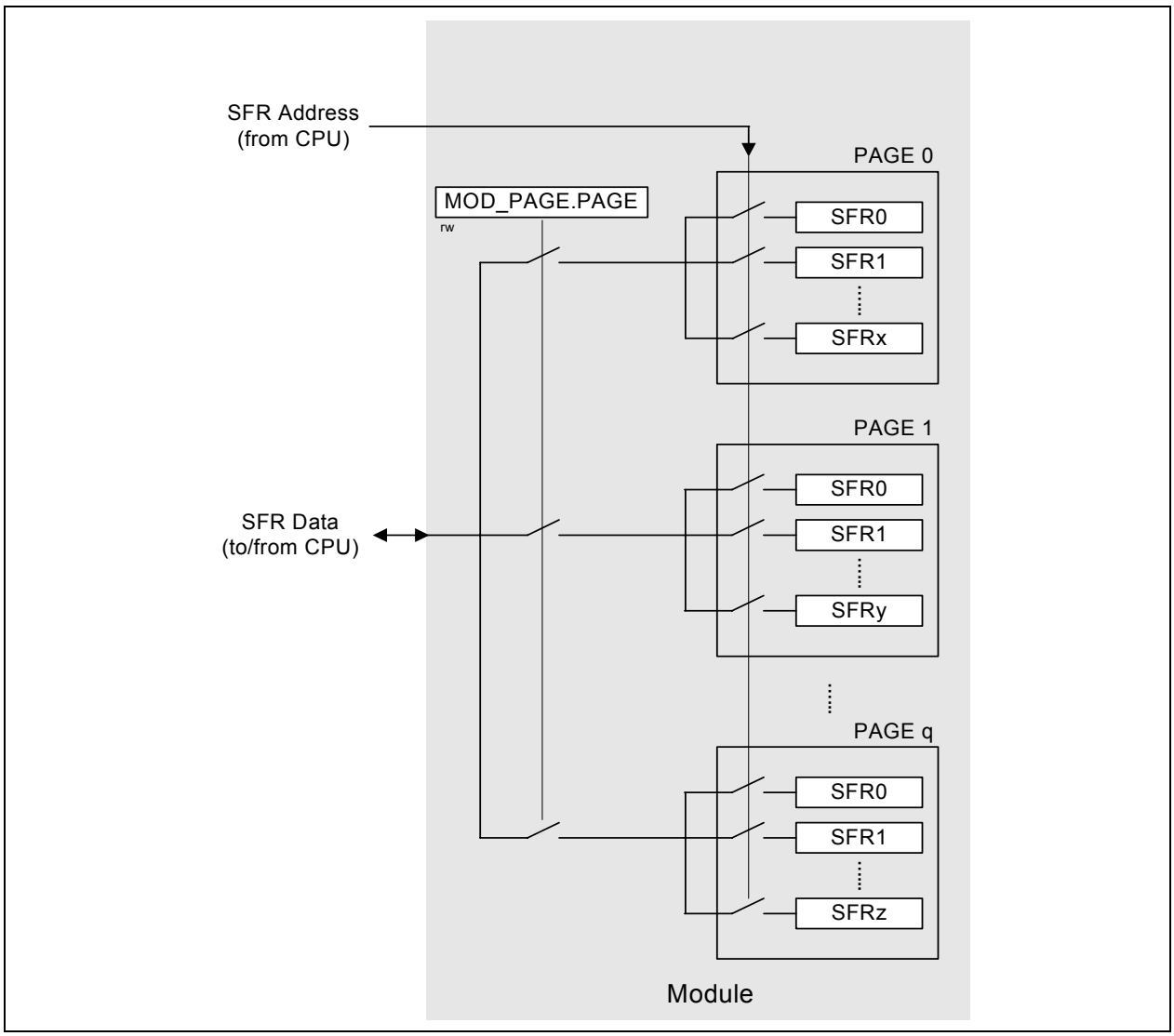


Figure 9 Address Extension by Paging

In order to access a register located in a page different from the actual one, the current page must be exited. This is done by reprogramming the bit field PAGE in the page register. Only then can the desired access be performed.

If an interrupt routine is initiated between the page register access and the module register access, and the interrupt needs to access a register located in another page, the current page setting can be saved, the new one programmed and the old page setting restored. This is possible with the storage fields STx (x = 0 - 3) for the save and restore action of the current page setting. By indicating which storage bit field should be used in parallel with the new page value, a single write operation can:

- Save the contents of PAGE in STx before overwriting with the new value
  (this is done in the beginning of the interrupt routine to save the current page setting and program the new page number); or

- Overwrite the contents of PAGE with the contents of STx, ignoring the value written to the bit positions of PAGE
  (this is done at the end of the interrupt routine to restore the previous page setting before the interrupt occurred)

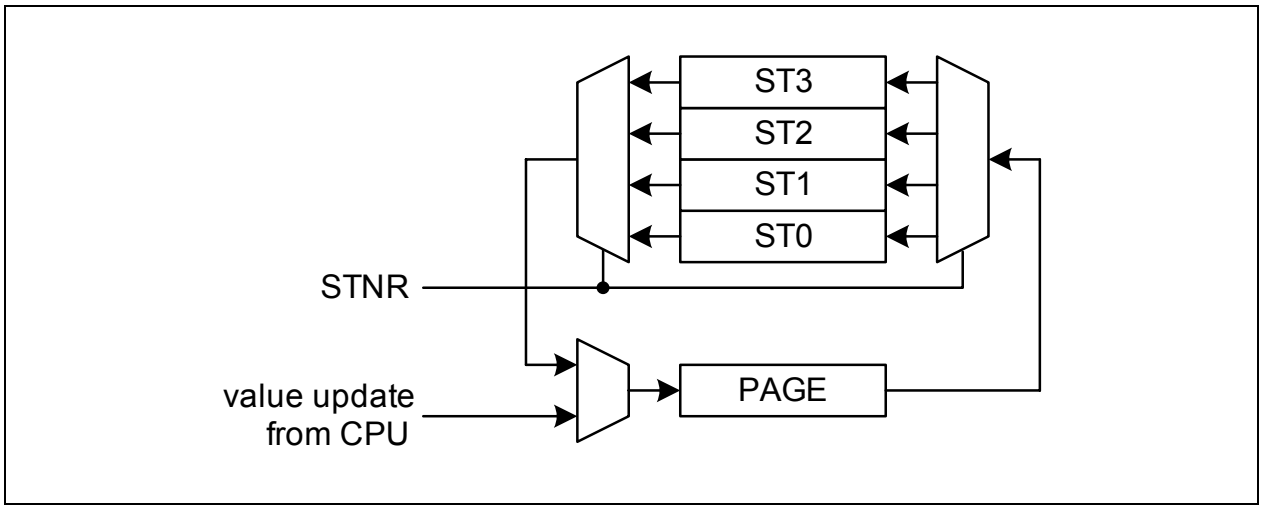


Figure 10 Storage Elements for Paging

With this mechanism, a certain number of interrupt routines (or other routines) can perform page changes without reading and storing the previously used page information. The use of only write operations makes the system simpler and faster. Consequently, this mechanism significantly improves the performance of short interrupt routines.

The XC886/888 supports local address extension for:

- Parallel Ports
- Analog-to-Digital Converter (ADC)
- Capture/Compare Unit 6 (CCU6)
- System Control Registers

Table 7 CORDIC Register Overview (cont'd)

Addr	Register Name	Bit	7	6	5	4	3	2	1	0
$A0_H$	**CD_STATC** **Reset: 00_H** CORDIC Status and Data Control Register	Bit Field	KEEPZ	KEEPY	KEEPX	DMAP	INT_EN	EOC	ERROR	BSY
		Type	rw	rw	rw	rw	rw	rwh	rh	rh
$A1_H$	**CD_CON** **Reset: 00_H** CORDIC Control Register	Bit Field	MPS		X_USIGN	ST_MODE	ROTVEC	MODE		ST
		Type	rw		rw	rw	rw	rw		rwh

3.2.4.4 System Control Registers

The system control SFRs can be accessed in the mapped memory area (RMAP = 0).

Table 8 SCU Register Overview

Addr	Register Name	Bit	7	6	5	4	3	2	1	0
RMAP = 0 or 1										
$8F_H$	**SYSCON0** **Reset: 04_H** System Control Register 0	Bit Field	0			IMODE	0	1	0	RMAP
		Type	r			rw	r	r	r	rw
RMAP = 0										
BF_H	**SCU_PAGE** **Reset: 00_H** Page Register	Bit Field	OP		STNR		0	PAGE		
		Type	w		w		r	rw		
RMAP = 0, PAGE 0										
$B3_H$	**MODPISEL** **Reset: 00_H** Peripheral Input Select Register	Bit Field	0	URRISH	JTAGTDIS	JTAGTCKS	EXINT2IS	EXINT1IS	EXINT0IS	URRIS
		Type	r	rw	rw	rw	rw	rw	rw	rw
$B4_H$	**IRCON0** **Reset: 00_H** Interrupt Request Register 0	Bit Field	0	EXINT6	EXINT5	EXINT4	EXINT3	EXINT2	EXINT1	EXINT0
		Type	r	rwh	rwh	rwh	rwh	rwh	rwh	rwh
$B5_H$	**IRCON1** **Reset: 00_H** Interrupt Request Register 1	Bit Field	0	CANSRC2	CANSRC1	ADCSR1	ADCSR0	RIR	TIR	EIR
		Type	r	rwh	rwh	rwh	rwh	rwh	rwh	rwh
$B6_H$	**IRCON2** **Reset: 00_H** Interrupt Request Register 2	Bit Field	0			CANSRC3	0			CANSRC0
		Type	r			rwh	r			rwh
$B7_H$	**EXICON0** **Reset: $F0_H$** External Interrupt Control Register 0	Bit Field	EXINT3		EXINT2		EXINT1		EXINT0	
		Type	rw		rw		rw		rw	
BA_H	**EXICON1** **Reset: $3F_H$** External Interrupt Control Register 1	Bit Field	0		EXINT6		EXINT5		EXINT4	
		Type	r		rw		rw		rw	
BB_H	**NMICON** **Reset: 00_H** NMI Control Register	Bit Field	0	NMIECC	NMIVDDP	NMIVDD	NMIOCDS	NMIFLASH	NMIPLL	NMIWDT
		Type	r	rw	rw	rw	rw	rw	rw	rw

Table 9 WDT Register Overview (cont'd)

Addr	Register Name	Bit	7	6	5	4	3	2	1	0
BE_H	**WDTL** **Reset: 00_H** Watchdog Timer Register Low	Bit Field	WDT							
		Type	rh							
BF_H	**WDTH** **Reset: 00_H** Watchdog Timer Register High	Bit Field	WDT							
		Type	rh							

3.2.4.6 Port Registers

The Port SFRs can be accessed in the standard memory area (RMAP = 0).

Table 10 Port Register Overview

Addr	Register Name	Bit	7	6	5	4	3	2	1	0
RMAP = 0										
$B2_H$	**PORT_PAGE** **Reset: 00_H** Page Register	Bit Field	OP		STNR		0	PAGE		
		Type	w		w		r	rw		
RMAP = 0, PAGE 0										
80_H	**P0_DATA** **Reset: 00_H** P0 Data Register	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rw	rw	rw	rw	rw	rw	rw	rw
86_H	**P0_DIR** **Reset: 00_H** P0 Direction Register	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rw	rw	rw	rw	rw	rw	rw	rw
90_H	**P1_DATA** **Reset: 00_H** P1 Data Register	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rw	rw	rw	rw	rw	rw	rw	rw
91_H	**P1_DIR** **Reset: 00_H** P1 Direction Register	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rw	rw	rw	rw	rw	rw	rw	rw
92_H	**P5_DATA** **Reset: 00_H** P5 Data Register	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rw	rw	rw	rw	rw	rw	rw	rw
93_H	**P5_DIR** **Reset: 00_H** P5 Direction Register	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rw	rw	rw	rw	rw	rw	rw	rw
$A0_H$	**P2_DATA** **Reset: 00_H** P2 Data Register	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rw	rw	rw	rw	rw	rw	rw	rw
$A1_H$	**P2_DIR** **Reset: 00_H** P2 Direction Register	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rw	rw	rw	rw	rw	rw	rw	rw
$B0_H$	**P3_DATA** **Reset: 00_H** P3 Data Register	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rw	rw	rw	rw	rw	rw	rw	rw
$B1_H$	**P3_DIR** **Reset: 00_H** P3 Direction Register	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rw	rw	rw	rw	rw	rw	rw	rw
$C8_H$	**P4_DATA** **Reset: 00_H** P4 Data Register	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rw	rw	rw	rw	rw	rw	rw	rw
$C9_H$	**P4_DIR** **Reset: 00_H** P4 Direction Register	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rw	rw	rw	rw	rw	rw	rw	rw

Table 14 CCU6 Register Overview (cont'd)

Addr	Register Name	Bit	7	6	5	4	3	2	1	0
FE_H	**CCU6_CMPSTATL Reset: 00_H** Compare State Register Low	Bit Field	0	CC63 ST	CC POS2	CC POS1	CC POS0	CC62 ST	CC61 ST	CC60 ST
		Type	r	rh	rh	rh	rh	rh	rh	rh
FF_H	**CCU6_CMPSTATH Reset: 00_H** Compare State Register High	Bit Field	T13IM	COUT 63PS	COUT 62PS	CC62 PS	COUT 61PS	CC61 PS	COUT 60PS	CC60 PS
		Type	rwh	rwh	rwh	rwh	rwh	rwh	rwh	rwh

3.2.4.11 UART1 Registers

The UART1 SFRs can be accessed in the mapped memory area (RMAP = 1).

Table 15 UART1 Register Overview

Addr	Register Name	Bit	7	6	5	4	3	2	1	0
RMAP = 1										
$C8_H$	**SCON Reset: 00_H** Serial Channel Control Register	Bit Field	SM0	SM1	SM2	REN	TB8	RB8	TI	RI
		Type	rw	rw	rw	rw	rw	rwh	rwh	rwh
$C9_H$	**SBUF Reset: 00_H** Serial Data Buffer Register	Bit Field	VAL							
		Type	rwh							
CA_H	**BCON Reset: 00_H** Baud Rate Control Register	Bit Field	0				BRPRE			R
		Type	r				rw			rw
CB_H	**BG Reset: 00_H** Baud Rate Timer/Reload Register	Bit Field	BR_VALUE							
		Type	rwh							
CC_H	**FDCON Reset: 00_H** Fractional Divider Control Register	Bit Field	0					NDOV	FDM	FDEN
		Type	r					rwh	rw	rw
CD_H	**FDSTEP Reset: 00_H** Fractional Divider Reload Register	Bit Field	STEP							
		Type	rw							
CE_H	**FDRES Reset: 00_H** Fractional Divider Result Register	Bit Field	RESULT							
		Type	rh							

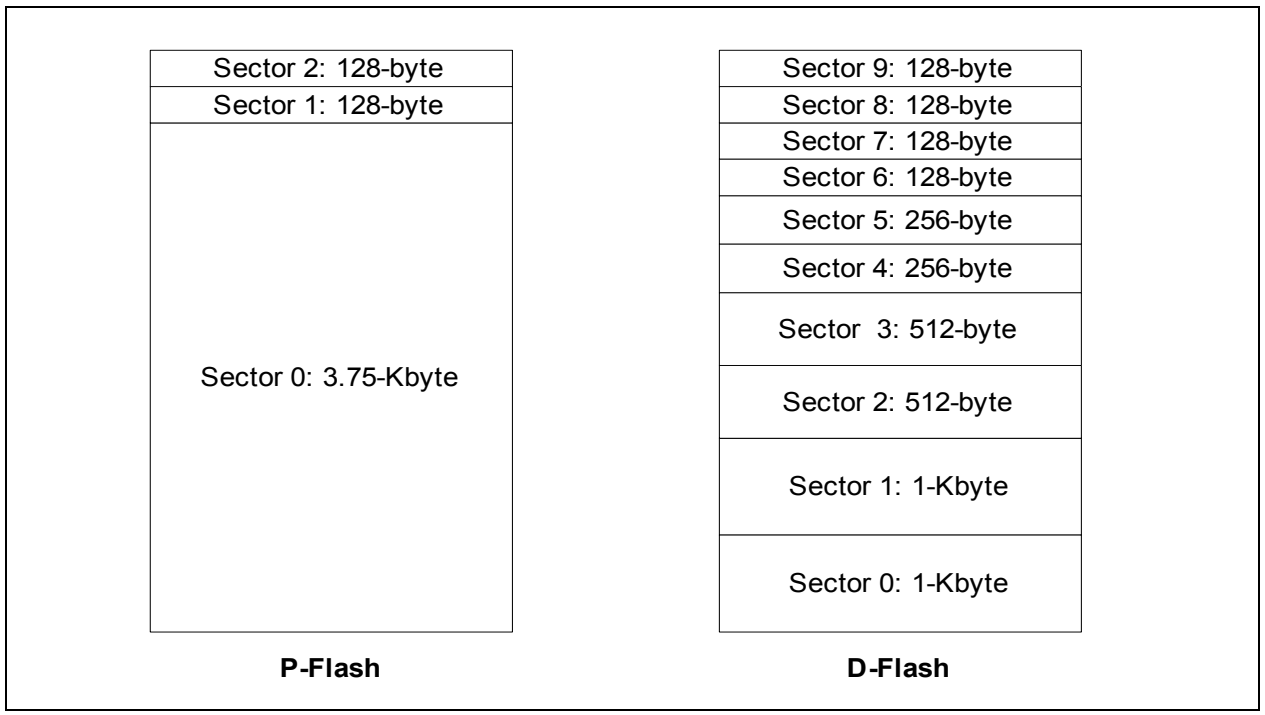


Figure 11 Flash Bank Sectorization

The internal structure of each Flash bank represents a sector architecture for flexible erase capability. The minimum erase width is always a complete sector, and sectors can be erased separately or in parallel. Contrary to standard EPROMs, erased Flash memory cells contain 0s.

The D-Flash bank is divided into more physical sectors for extended erasing and reprogramming capability; even numbers for each sector size are provided to allow greater flexibility and the ability to adapt to a wide range of application requirements.

3.3.2 Parallel Read Access of P-Flash

To enhance system performance, the P-Flash banks are configured for parallel read to allow two bytes of linear code to be read in 4 x CCLK cycles, compared to 6 x CCLK cycles if serial read is performed. This is achieved by reading two bytes in parallel from a P-Flash bank pair within the 3 x CCLK cycles access time and storing them in a cache. Subsequent read from the cache by the CPU does not require a wait state and can be completed within 1 x CCLK cycle. The result is the average instruction fetch time from the P-Flash banks is reduced and thus, the MIPS (Mega Instruction Per Second) of the system is increased.

However, if the parallel read feature is not desired due to certain timing constraints, it can be disabled by calling the parallel read disable subroutine.

3.7.1 Module Reset Behavior

Table 22 lists the functions of the XC886/888 and the various reset types that affect these functions. The symbol "■" signifies that the particular function is reset to its default state.

Table 22 Effect of Reset on Device Functions

Module/ Function	Wake-Up Reset	Watchdog Reset	Hardware Reset	Power-On Reset	Brownout Reset
CPU Core	■	■	■	■	■
Peripherals	■	■	■	■	■
On-Chip Static RAM	Not affected, Reliable	Not affected, Reliable	Not affected, Reliable	Affected, un-reliable	Affected, un-reliable
Oscillator, PLL	■	Not affected	■	■	■
Port Pins	■	■	■	■	■
EVR	The voltage regulator is switched on	Not affected	■	■	■
FLASH	■	■	■	■	■
NMI	Disabled	Disabled	■	■	■

3.7.2 Booting Scheme

When the XC886/888 is reset, it must identify the type of configuration with which to start the different modes once the reset sequence is complete. Thus, boot configuration information that is required for activation of special modes and conditions needs to be applied by the external world through input pins. After power-on reset or hardware reset, the pins MBC, TMS and P0.0 collectively select the different boot options. Table 23 shows the available boot options in the XC886/888.

Table 23 XC886/888 Boot Selection

MBC	TMS	P0.0	Type of Mode	PC Start Value
1	0	X	User Mode[1]; on-chip OSC/PLL non-bypassed	0000_H
0	0	X	BSL Mode; on-chip OSC/PLL non-bypassed[2]	0000_H
0	1	0	OCDS Mode; on-chip OSC/PLL non-bypassed	0000_H
1	1	0	User (JTAG) Mode[3]; on-chip OSC/PLL non-bypassed (normal)	0000_H

If the WDT is not serviced before the timer overflow, a system malfunction is assumed. As a result, the WDT NMI is triggered (assert FNMIWDT) and the reset prewarning is entered. The prewarning period lasts for 30_H count, after which the system is reset (assert WDTRST).

The WDT has a “programmable window boundary” which disallows any refresh during the WDT’s count-up. A refresh during this window boundary constitutes an invalid access to the WDT, causing the reset prewarning to be entered but without triggering the WDT NMI. The system will still be reset after the prewarning period is over. The window boundary is from 0000_H to the value obtained from the concatenation of WDTWINB and 00_H.

After being serviced, the WDT continues counting up from the value (<WDTREL> * 2^8). The time period for an overflow of the WDT is programmable in two ways:

- The input frequency to the WDT can be selected to be either $f_{PCLK}/2$ or $f_{PCLK}/128$
- The reload value WDTREL for the high byte of WDT can be programmed in register WDTREL

The period, P_{WDT}, between servicing the WDT and the next overflow can be determined by the following formula:

$$P_{WDT} = \frac{2^{(1 + WDTIN \times 6)} \times (2^{16} - WDTREL \times 2^8)}{f_{PCLK}} \quad (3.4)$$

If the Window-Boundary Refresh feature of the WDT is enabled, the period P_{WDT} between servicing the WDT and the next overflow is shortened if WDTWINB is greater than WDTREL, see **Figure 29**. This period can be calculated using the same formula by replacing WDTREL with WDTWINB. For this feature to be useful, WDTWINB cannot be smaller than WDTREL.

fractional divider) for generating a wide range of baud rates based on its input clock f_{PCLK}, see **Figure 30**.

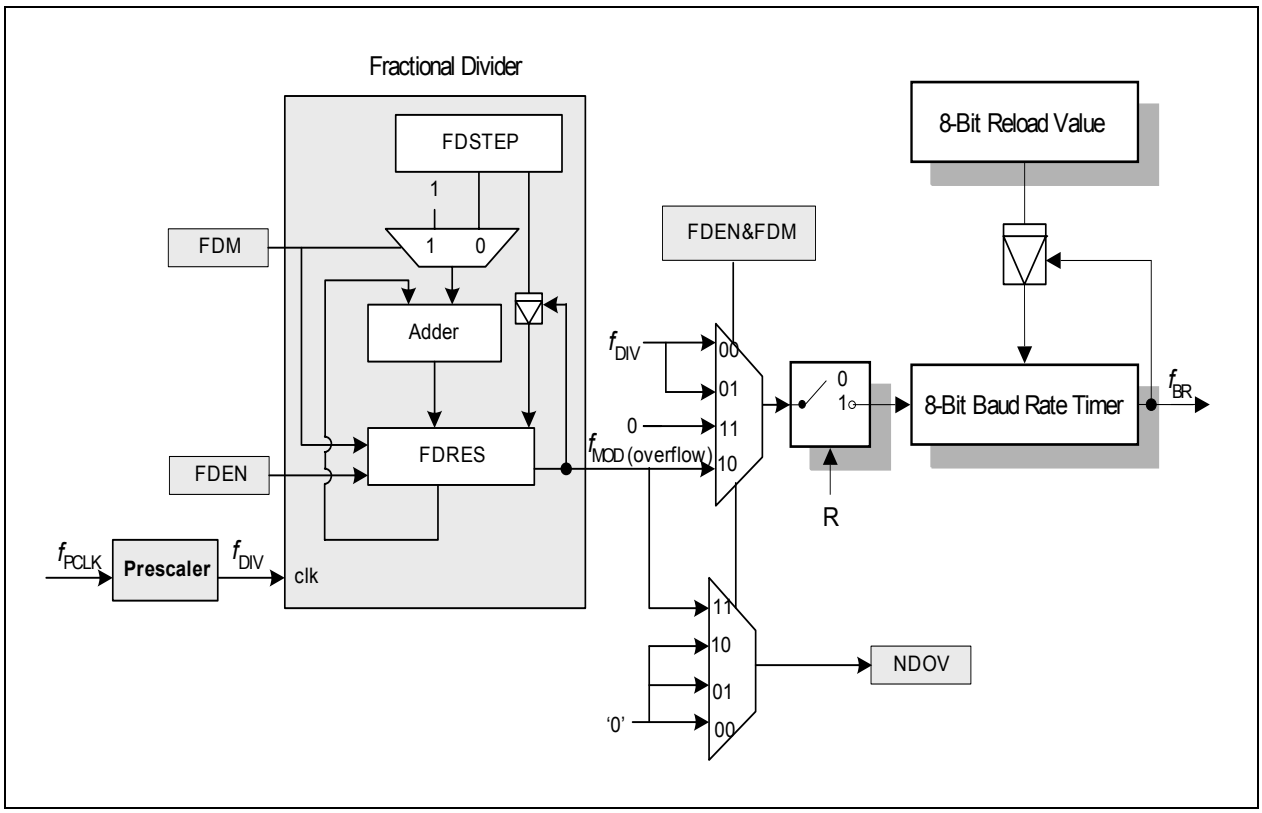


Figure 30 Baud-rate Generator Circuitry

The baud rate timer is a count-down timer and is clocked by either the output of the fractional divider (f_{MOD}) if the fractional divider is enabled (FDCON.FDEN = 1), or the output of the prescaler (f_{DIV}) if the fractional divider is disabled (FDEN = 0). For baud rate generation, the fractional divider must be configured to fractional divider mode (FDCON.FDM = 0). This allows the baud rate control run bit BCON.R to be used to start or stop the baud rate timer. At each timer underflow, the timer is reloaded with the 8-bit reload value in register BG and one clock pulse is generated for the serial channel.

Enabling the fractional divider in normal divider mode (FDEN = 1 and FDM = 1) stops the baud rate timer and nullifies the effect of bit BCON.R. See **Section 3.14**.

The baud rate (f_{BR}) value is dependent on the following parameters:

- Input clock f_{PCLK}
- Prescaling factor (2^{BRPRE}) defined by bit field BRPRE in register BCON
- Fractional divider (STEP/256) defined by register FDSTEP
  (to be considered only if fractional divider is enabled and operating in fractional divider mode)
- 8-bit reload value (BR_VALUE) for the baud rate timer defined by register BG

Table 31 Deviation Error for UART with Fractional Divider enabled

f_{PCLK}	Prescaling Factor (2BRPRE)	Reload Value (BR_VALUE + 1)	STEP	Deviation Error
24 MHz	1	10 (A_H)	197 ($C5_H$)	+0.20 %
12 MHz	1	6 (6_H)	236 (EC_H)	+0.03 %
8 MHz	1	4 (4_H)	236 (EC_H)	+0.03 %
6 MHz	1	3 (3_H)	236 (EC_H)	+0.03 %

3.13.2 Baud Rate Generation using Timer 1

In UART modes 1 and 3 of UART module, Timer 1 can be used for generating the variable baud rates. In theory, this timer could be used in any of its modes. But in practice, it should be set into auto-reload mode (Timer 1 mode 2), with its high byte set to the appropriate value for the required baud rate. The baud rate is determined by the Timer 1 overflow rate and the value of SMOD as follows:

$$\text{Mode 1, 3 baud rate} = \frac{2^{SMOD} \times f_{PCLK}}{32 \times 2 \times (256 - TH1)} \quad (3.7)$$

3.14 Normal Divider Mode (8-bit Auto-reload Timer)

Setting bit FDM in register FDCON to 1 configures the fractional divider to normal divider mode, while at the same time disables baud rate generation (see **Figure 30**). Once the fractional divider is enabled (FDEN = 1), it functions as an 8-bit auto-reload timer (with no relation to baud rate generation) and counts up from the reload value with each input clock pulse. Bit field RESULT in register FDRES represents the timer value, while bit field STEP in register FDSTEP defines the reload value. At each timer overflow, an overflow flag (FDCON.NDOV) will be set and an interrupt request generated. This gives an output clock f_{MOD} that is 1/n of the input clock f_{DIV}, where n is defined by 256 - STEP.

The output frequency in normal divider mode is derived as follows:

$$f_{MOD} = f_{DIV} \times \frac{1}{256 - STEP} \quad (3.8)$$

3.22 On-Chip Debug Support

The On-Chip Debug Support (OCDS) provides the basic functionality required for the software development and debugging of XC800-based systems.

The OCDS design is based on these principles:

- Use the built-in debug functionality of the XC800 Core
- Add a minimum of hardware overhead
- Provide support for most of the operations by a Monitor Program
- Use standard interfaces to communicate with the Host (a Debugger)

Features

- Set breakpoints on instruction address and on address range within the Program Memory
- Set breakpoints on internal RAM address range
- Support unlimited software breakpoints in Flash/RAM code region
- Process external breaks via JTAG and upon activating a dedicated pin
- Step through the program code

The OCDS functional blocks are shown in **Figure 37**. The Monitor Mode Control (MMC) block at the center of OCDS system brings together control signals and supports the overall functionality. The MMC communicates with the XC800 Core, primarily via the Debug Interface, and also receives reset and clock signals.

After processing memory address and control signals from the core, the MMC provides proper access to the dedicated extra-memories: a Monitor ROM (holding the code) and a Monitor RAM (for work-data and Monitor-stack).

The OCDS system is accessed through the JTAG[1)], which is an interface dedicated exclusively for testing and debugging activities and is not normally used in an application. The dedicated MBC pin is used for external configuration and debugging control.

Note: All the debug functionality described here can normally be used only after XC886/888 has been started in OCDS mode.

1) The pins of the JTAG port can be assigned to either the primary port (Port 0) or either of the secondary ports (Ports 1 and 2/Port 5).
User must set the JTAG pins (TCK and TDI) as input during connection with the OCDS system.

Table 36 Chip Identification Number (cont'd)

Product Variant	Chip Identification Number		
	AA-Step	**AB-Step**	**AC-Step**
XC886-6FFA 3V3	-	$095D1562_H$	$0B5D1562_H$
XC888-6FFA 3V3	-	$095D1563_H$	$0B5D1563_H$
XC886CLM-8FFA 5V	-	09900102_H	$0B900102_H$
XC888CLM-8FFA 5V	-	09900103_H	$0B900103_H$
XC886LM-8FFA 5V	-	09900122_H	$0B900122_H$
XC888LM-8FFA 5V	-	09900123_H	$0B900123_H$
XC886CLM-6FFA 5V	-	09951502_H	$0B951502_H$
XC888CLM-6FFA 5V	-	09951503_H	$0B951503_H$
XC886LM-6FFA 5V	-	09951522_H	$0B951522_H$
XC888LM-6FFA 5V	-	09951523_H	$0B951523_H$
XC886CM-8FFA 5V	-	09980102_H	$0B980102_H$
XC888CM-8FFA 5V	-	09980103_H	$0B980103_H$
XC886C-8FFA 5V	-	09980142_H	$0B980142_H$
XC888C-8FFA 5V	-	09980143_H	$0B980143_H$
XC886-8FFA 5V	-	09980162_H	$0B980162_H$
XC888-8FFA 5V	-	09980163_H	$0B980163_H$
XC886CM-6FFA 5V	-	$099D1502_H$	$0B9D1502_H$
XC888CM-6FFA 5V	-	$099D1503_H$	$0B9D1503_H$
XC886C-6FFA 5V	-	$099D1542_H$	$0B9D1542_H$
XC888C-6FFA 5V	-	$099D1543_H$	$0B9D1543_H$
XC886-6FFA 5V	-	$099D1562_H$	$0B9D1562_H$
XC888-6FFA 5V	-	$099D1563_H$	$0B9D1563_H$
ROM Devices			
XC886CLM-8RFA 3V3	22400502_H	-	-
XC888CLM-8RFA 3V3	22400503_H	-	-
XC886LM-8RFA 3V3	22400522_H	-	-
XC888LM-8RFA 3V3	22400523_H	-	-
XC886CLM-6RFA 3V3	22411502_H	-	-
XC888CLM-6RFA 3V3	22411503_H	-	-

Table 43 Power Supply Current Parameters (Operating Conditions apply; V_{DDP} = 3.3V range)

Parameter	Symbol	Limit Values		Unit	Test Condition
		typ.[1]	max.[2]		
V_{DDP} = 3.3V Range					
Active Mode	I_{DDP}	25.6	31.0	mA	Flash Device[3]
		23.4	28.6	mA	ROM Device[3]
Idle Mode	I_{DDP}	19.9	24.7	mA	Flash Device[4]
		17.5	20.7	mA	ROM Device[4]
Active Mode with slow-down enabled	I_{DDP}	13.3	16.2	mA	Flash Device[5]
		11.5	13.7	mA	ROM Device[5]
Idle Mode with slow-down enabled	I_{DDP}	11.1	14.4	mA	Flash Device[6]
		9.3	11.4	mA	ROM Device[6]

1) The typical I_{DDP} values are periodically measured at T_A = + 25 °C and V_{DDP} = 3.3 V.

2) The maximum I_{DDP} values are measured under worst case conditions (T_A = + 125 °C and V_{DDP} = 3.6 V).

3) I_{DDP} (active mode) is measured with: CPU clock and input clock to all peripherals running at 24 MHz(set by on-chip oscillator of 9.6 MHz and NDIV in PLL_CON to 1001_B), $\overline{\text{RESET}}$ = V_{DDP}, no load on ports.

4) I_{DDP} (idle mode) is measured with: CPU clock disabled, watchdog timer disabled, input clock to all peripherals enabled and running at 24 MHz, $\overline{\text{RESET}}$ = V_{DDP}, no load on ports.

5) I_{DDP} (active mode with slow-down mode) is measured with: CPU clock and input clock to all peripherals running at 8 MHz by setting CLKREL in CMCON to 0110_B, $\overline{\text{RESET}}$ = V_{DDP}, no load on ports.

6) I_{DDP} (idle mode with slow-down mode) is measured with: CPU clock disabled, watchdog timer disabled, input clock to all peripherals enabled and running at 8 MHz by setting CLKREL in CMCON to 0110_B,, $\overline{\text{RESET}}$ = V_{DDP}, no load on ports.

5 Package and Quality Declaration

Chapter 5 provides the information of the XC886/888 package and reliability section.

5.1 Package Parameters

Table 1 provides the thermal characteristics of the package used in XC886 and XC888.

Table 1 Thermal Characteristics of the Packages

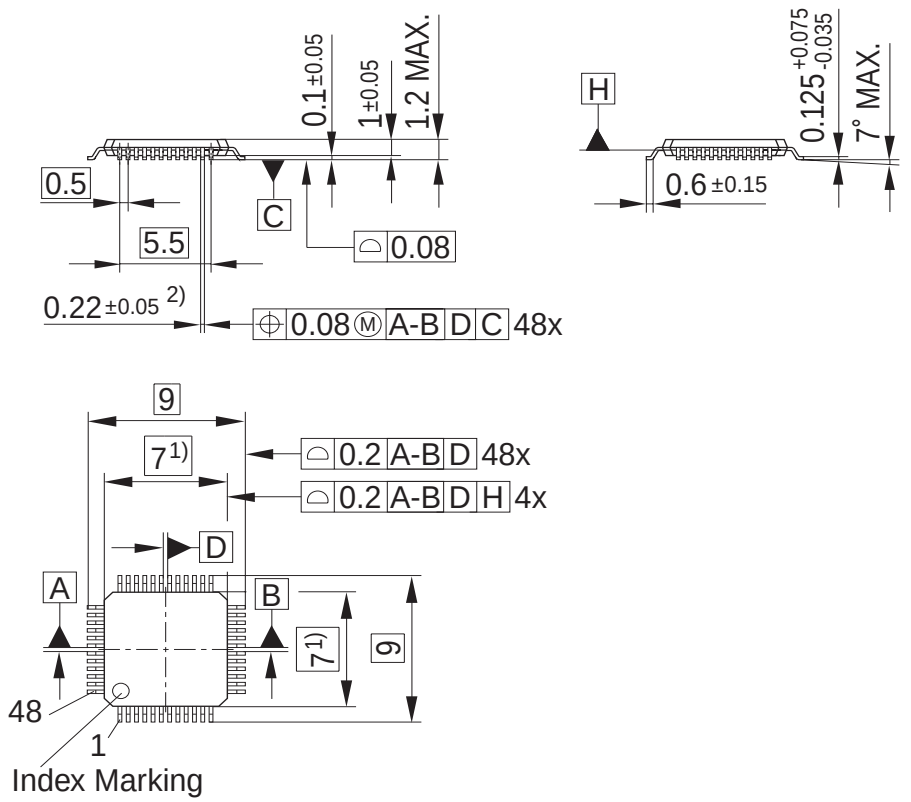
Parameter	Symbol		Limit Values		Unit	Notes
			Min.	Max.		
PG-TQFP-48 (XC886)						
Thermal resistance junction case	R_{TJC}	CC	-	13	K/W	1)2)
Thermal resistance junction lead	R_{TJL}	CC	-	32.5	K/W	1)2)
PG-TQFP-64 (XC888)						
Thermal resistance junction case	R_{TJC}	CC	-	12.6	K/W	1)2)
Thermal resistance junction lead	R_{TJL}	CC	-	33.4	K/W	1)2)

1) The thermal resistances between the case and the ambient (R_{TCA}) , the lead and the ambient (R_{TLA}) are to be combined with the thermal resistances between the junction and the case (R_{TJC}), the junction and the lead (R_{TJL}) given above, in order to calculate the total thermal resistance between the junction and the ambient (R_{TJA}). The thermal resistances between the case and the ambient (R_{TCA}), the lead and the ambient (R_{TLA}) depend on the external system (PCB, case) characteristics, and are under user responsibility.
The junction temperature can be calculated using the following equation: $T_J=T_A+R_{TJA} \times P_D$, where the R_{TJA} is the total thermal resistance between the junction and the ambient. This total junction ambient resistance R_{TJA} can be obtained from the upper four partial thermal resistances, by
a) simply adding only the two thermal resistances (junction lead and lead ambient), or
b) by taking all four resistances into account, depending on the precision needed.

2) Not all parameters are 100% tested, but are verified by design/characterization and test correlation.

5.2 Package Outline

Figure 48 shows the package outlines of the XC886.



1) Does not include plastic or metal protrusion of 0.25 max. per side
2) Does not include dambar protrusion of 0.08 max. per side

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Figure 48 PG-TQFP-48 Package Outline